

Abstract

A micropatterned thermosensor (5), in particular an infrared sensor, is proposed, having a supporting body (12) and at least one thermocouple (20) arranged thereon. The thermocouple (20) also has a first material (13) and a second material (14), which together form, at least in a pointwise manner, at least one thermal contact (10, 11). Furthermore, it is provided that the first and/or the second material (13, 14) are configured at least regionally in the form of a meander-shaped or undulating-type circuit trace (15, 16) and run on the supporting body (12). In addition, a micropatterned thermosensor (5) is proposed, preferably also having such patterned circuit traces (15, 16), in which the first material (13) is platinum or aluminum, and the second material (14) is doped or undoped polysilicon-germanium.

(Figure 1)